

# **Creep Properties of Lead-free Solder Joints**

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# Motivation

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- High homologous temperature during thermal fatigue means that creep is a major deformation mode.
- Creep behavior of Lead(Pb)-free solder joints in shear must be known to use them reliably in microelectronic applications.

# Pb-Free Solders of Interest in This Work

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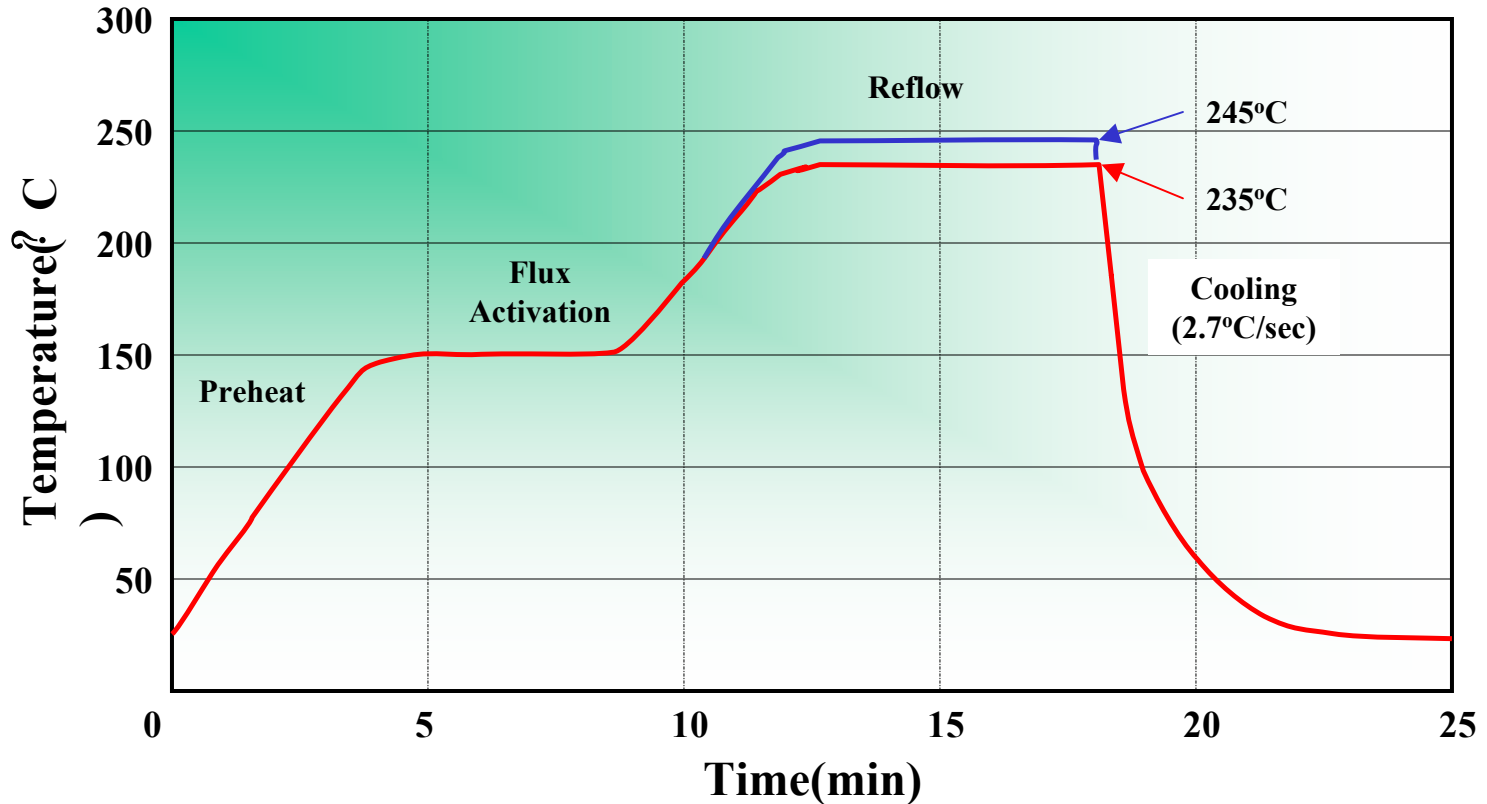
<b>Solder System</b>	<b>M.P.(?C)</b>	<b>Constituent phases</b>	<b>T/T<sub>m</sub> at R.T.</b>
<b>Sn-0.7Cu</b>	227	$\beta$ -Sn, Cu <sub>6</sub> Sn <sub>5</sub>	0.596
<b>Sn-3.5Ag</b>	221	$\beta$ -Sn, Ag <sub>3</sub> Sn	0.603
<b>Sn-10In-3.1Ag</b>	204	$\beta$ -Sn, Ag <sub>2</sub> In, $\gamma$ -InSn	0.625
<b>Sn-3Ag-0.5Cu</b>	218	$\beta$ -Sn, Ag <sub>3</sub> Sn, Cu <sub>6</sub> Sn <sub>5</sub>	0.607

# Experimental Procedure

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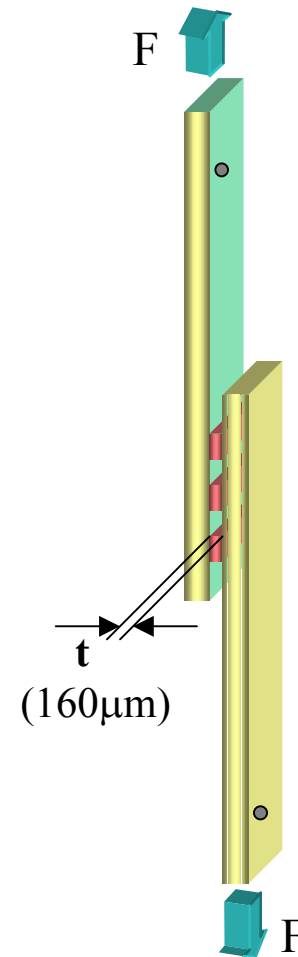
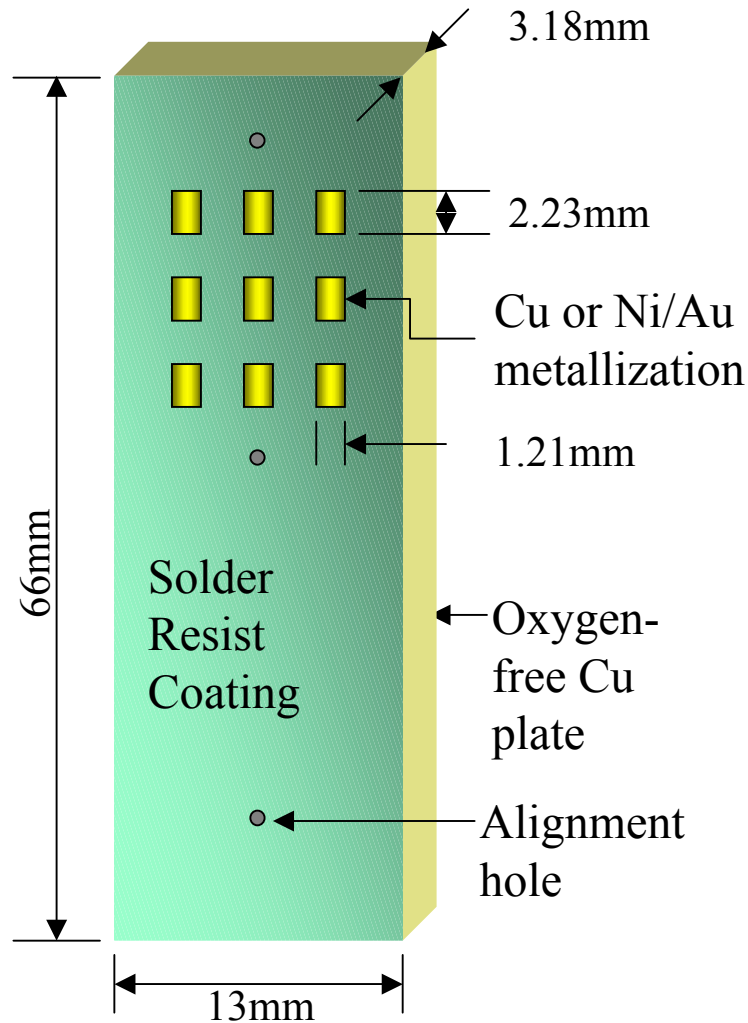
- Solder alloy manufacturing
  - Alloyed by vacuum arc melting
  - Rolled to make foil after homogenization
  - Punched to get the constant volume of solder
- Test specimen manufacturing
  - Manufactured solder masked Cu coupons with 9 pads
  - Assembled to single-shear specimens with bare Cu and electroless Ni/immersion Au plated coupons
  - Reflow and annealing
- Creep tests
  - Performed at 60, 95, 130°C under constant load conditions

# Reflow Profile (at N<sub>2</sub> atmosphere)



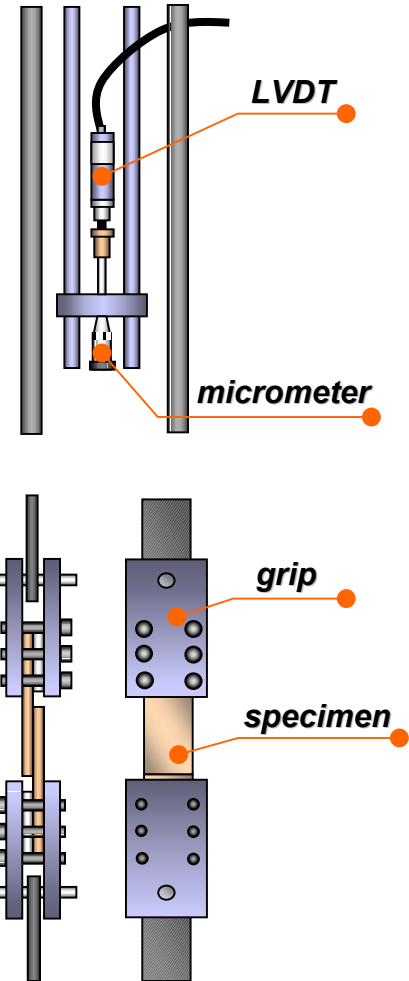
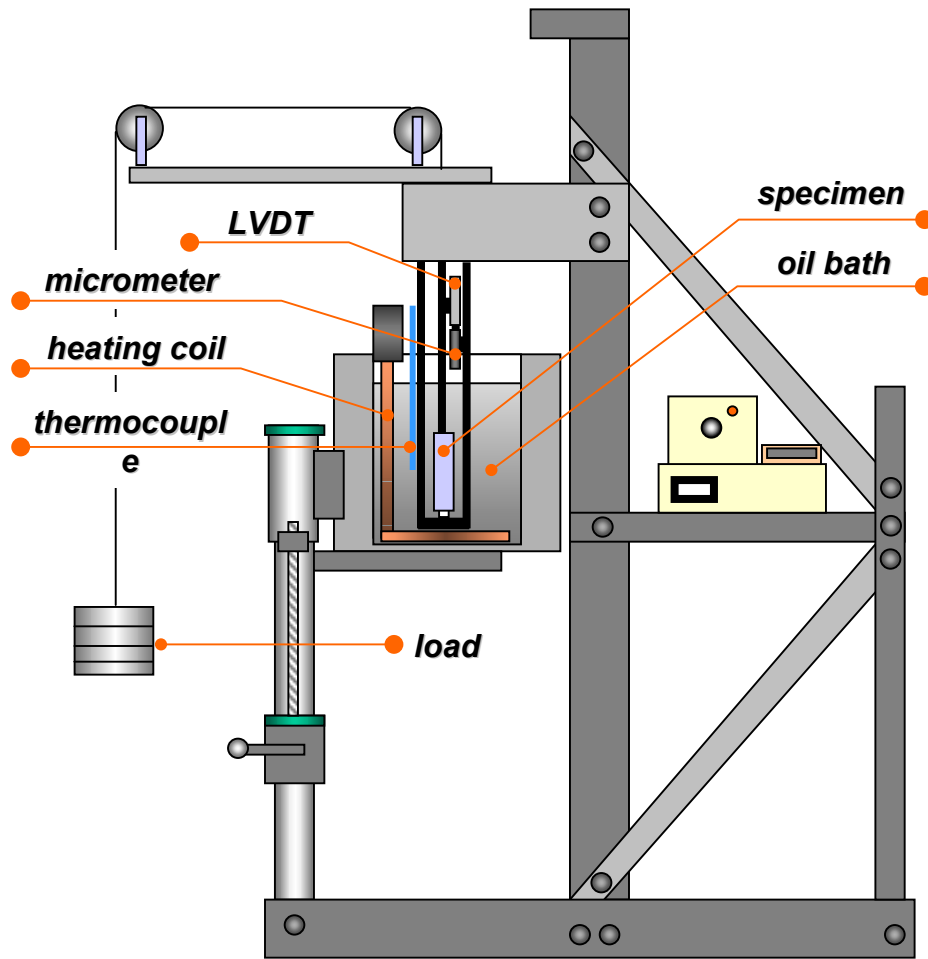
- Reflow peak temperature of 235°C for SnAg, SnInAg, SnAgCu and 245°C for SnCu
- Followed by aging at 160°C for 4 hours.

# Geometry of Single-Shear Specimen

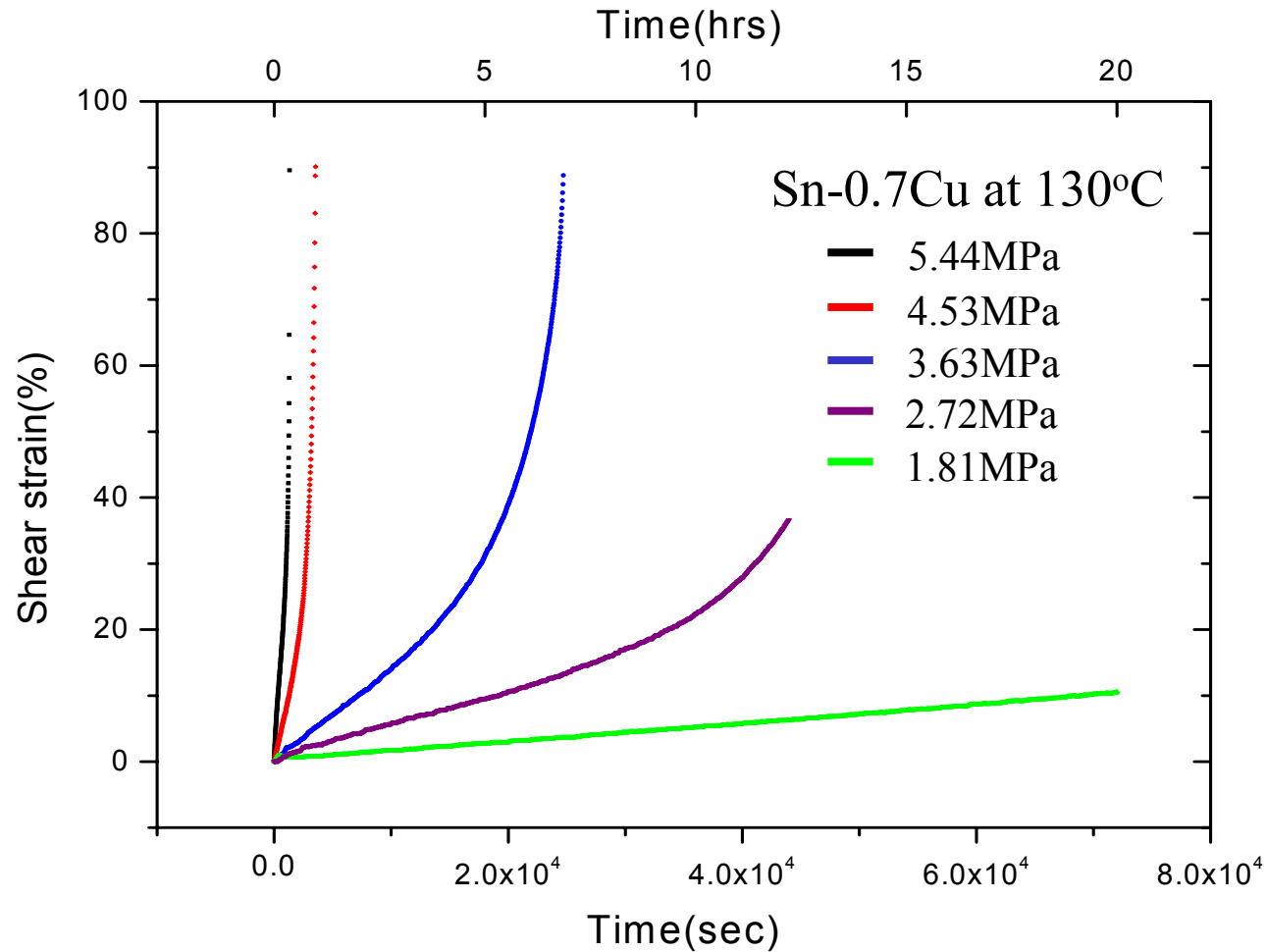


- One coupon has Cu pads
- One coupon has electroless Ni / immersion Au pads.

# Creep Test Apparatus

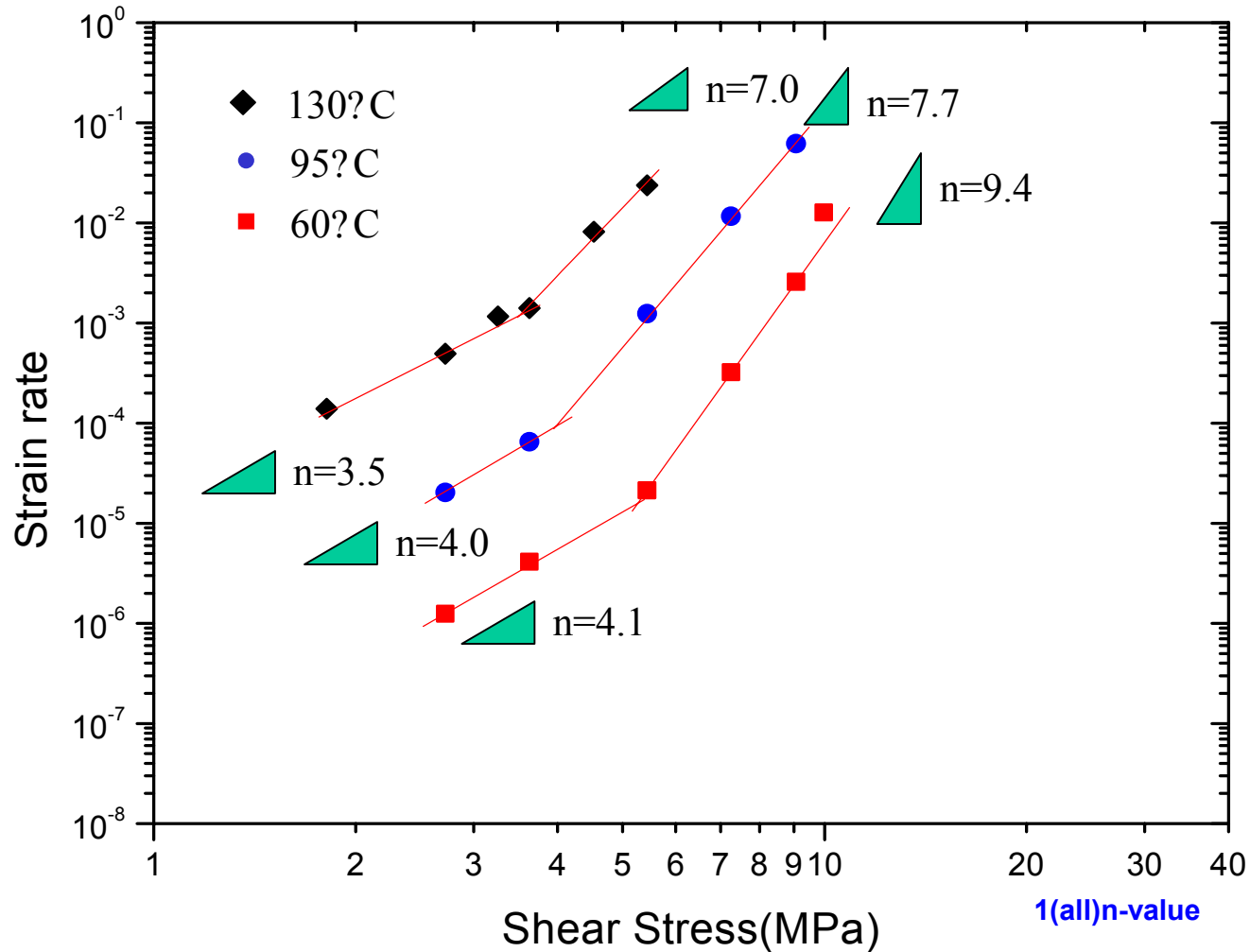


# Typical Creep Curves of Solder Joints

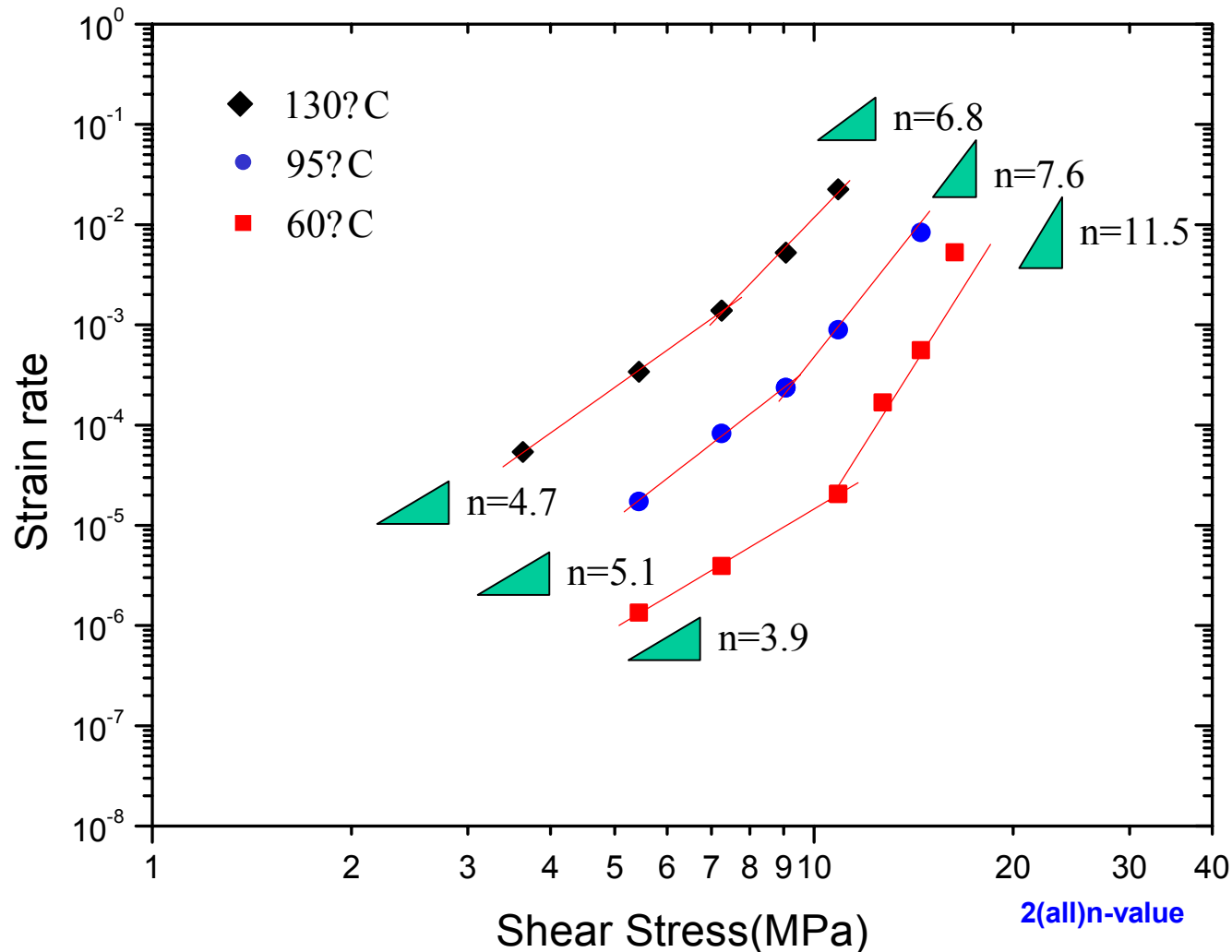




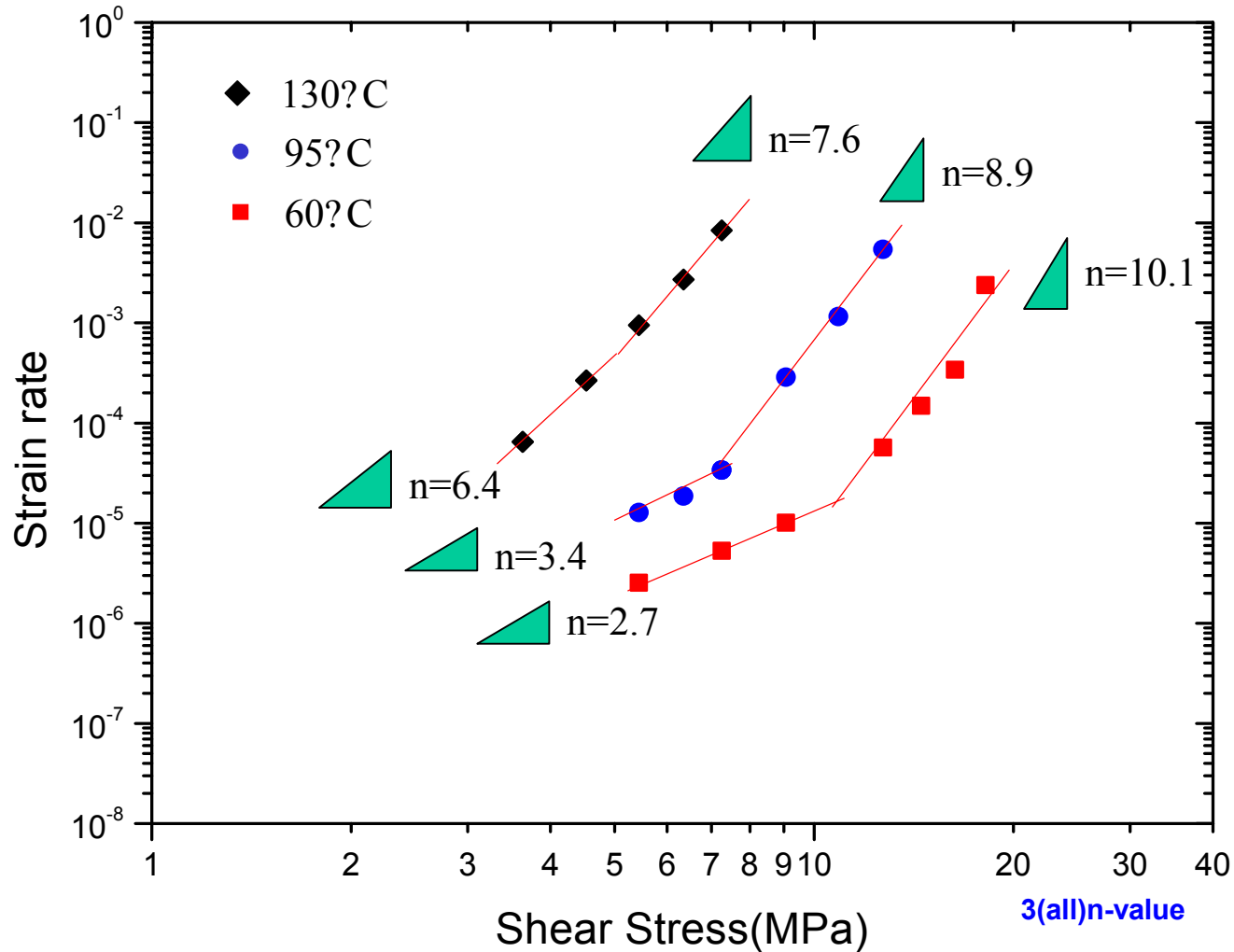
# SnCu: Shear Stress vs. Shear Strain rate



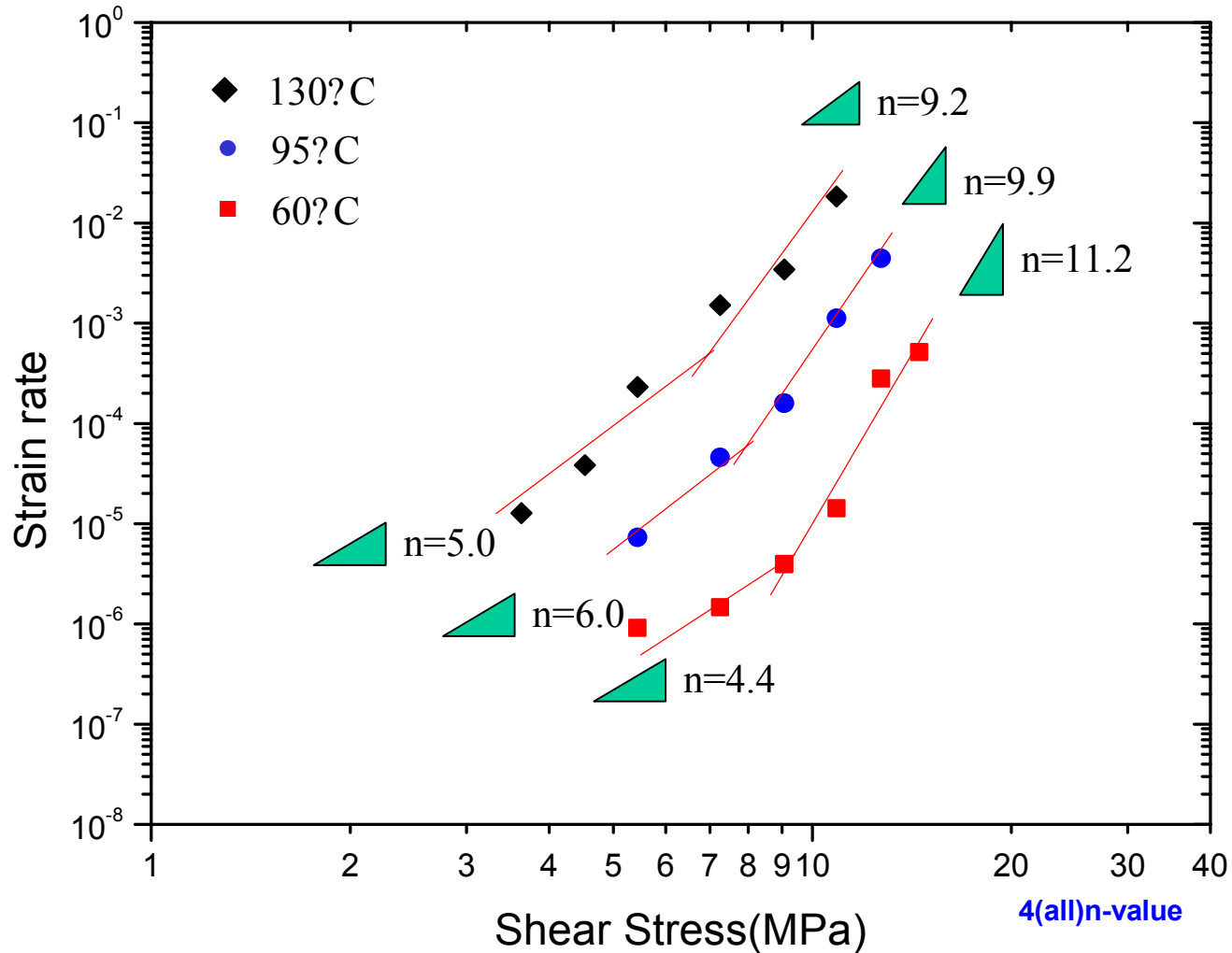
# SnAg: Shear Stress vs. Shear Strain rate



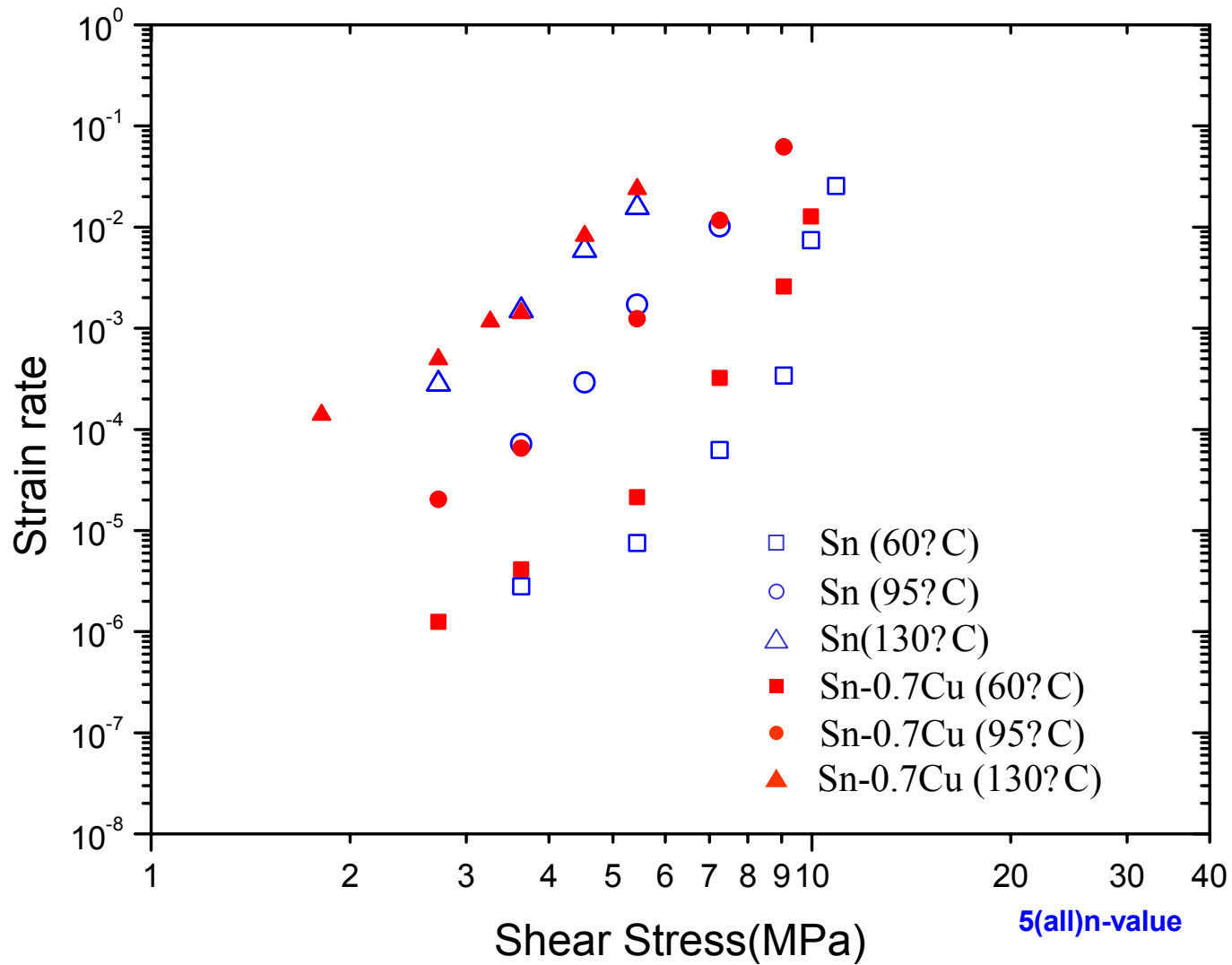
# SnInAg: Shear Stress vs. Shear Strain rate



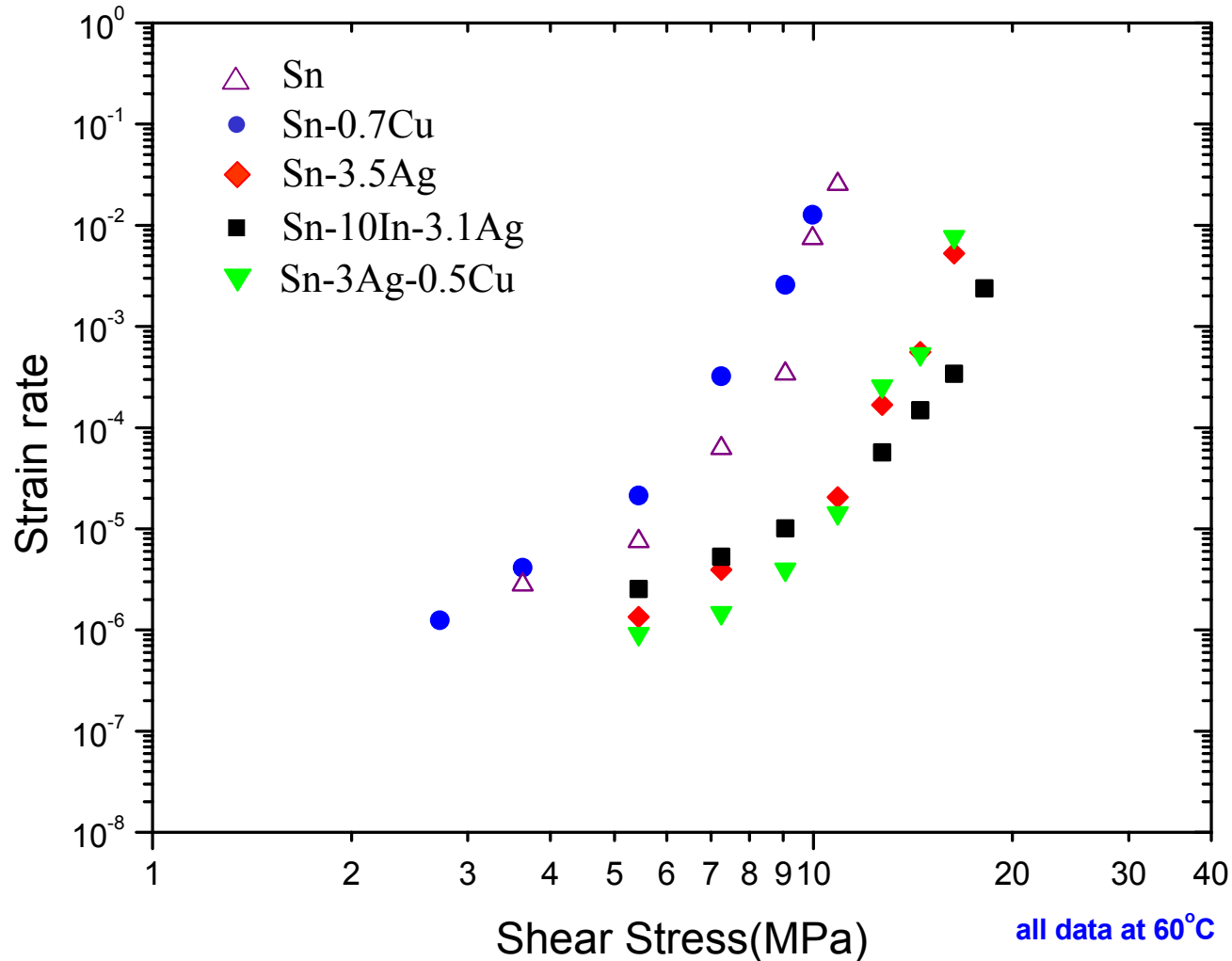
# SnAgCu: Shear Stress vs. Shear Strain rate



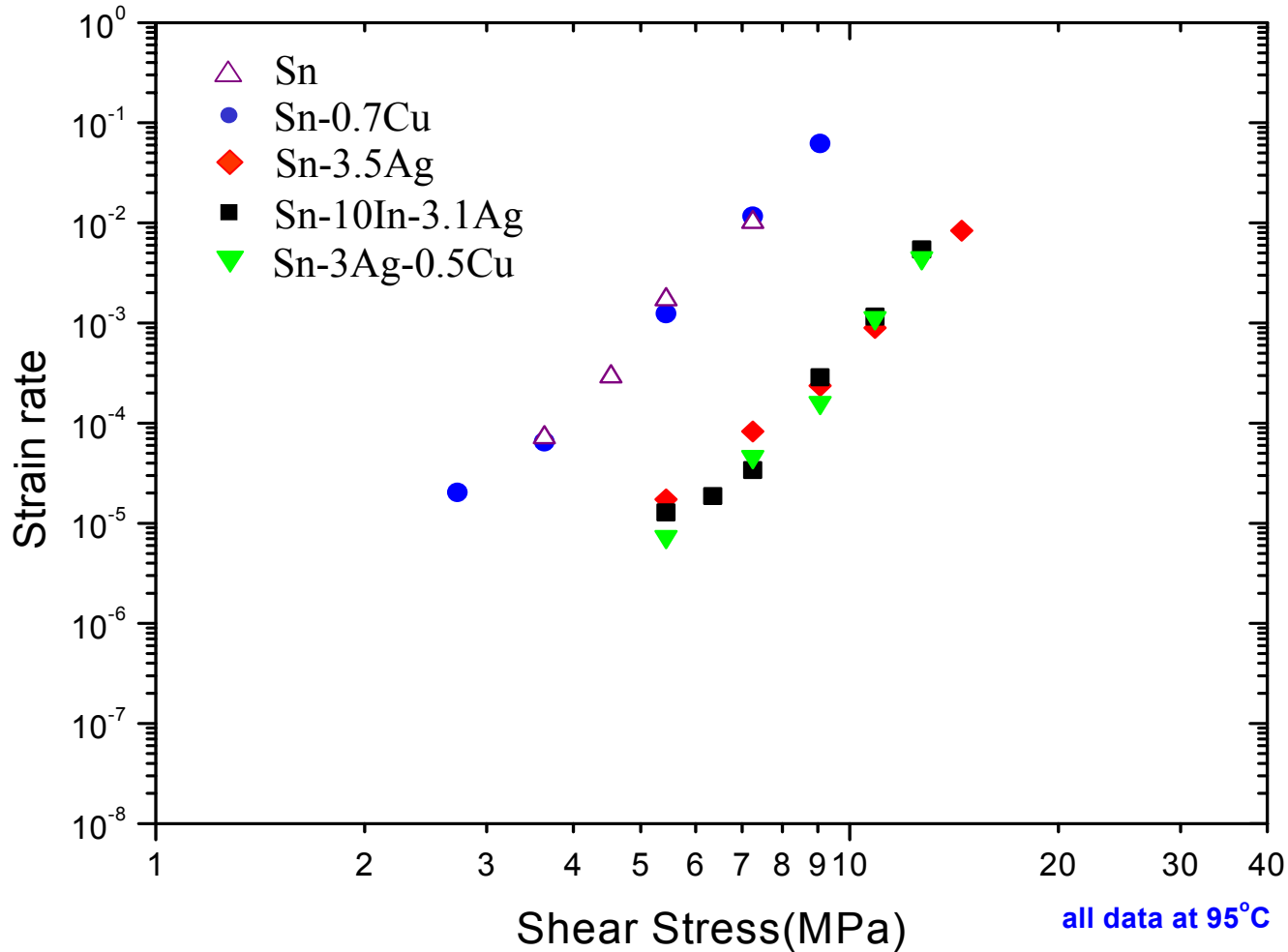
# Sn Joints vs. Sn-0.7Cu Joints



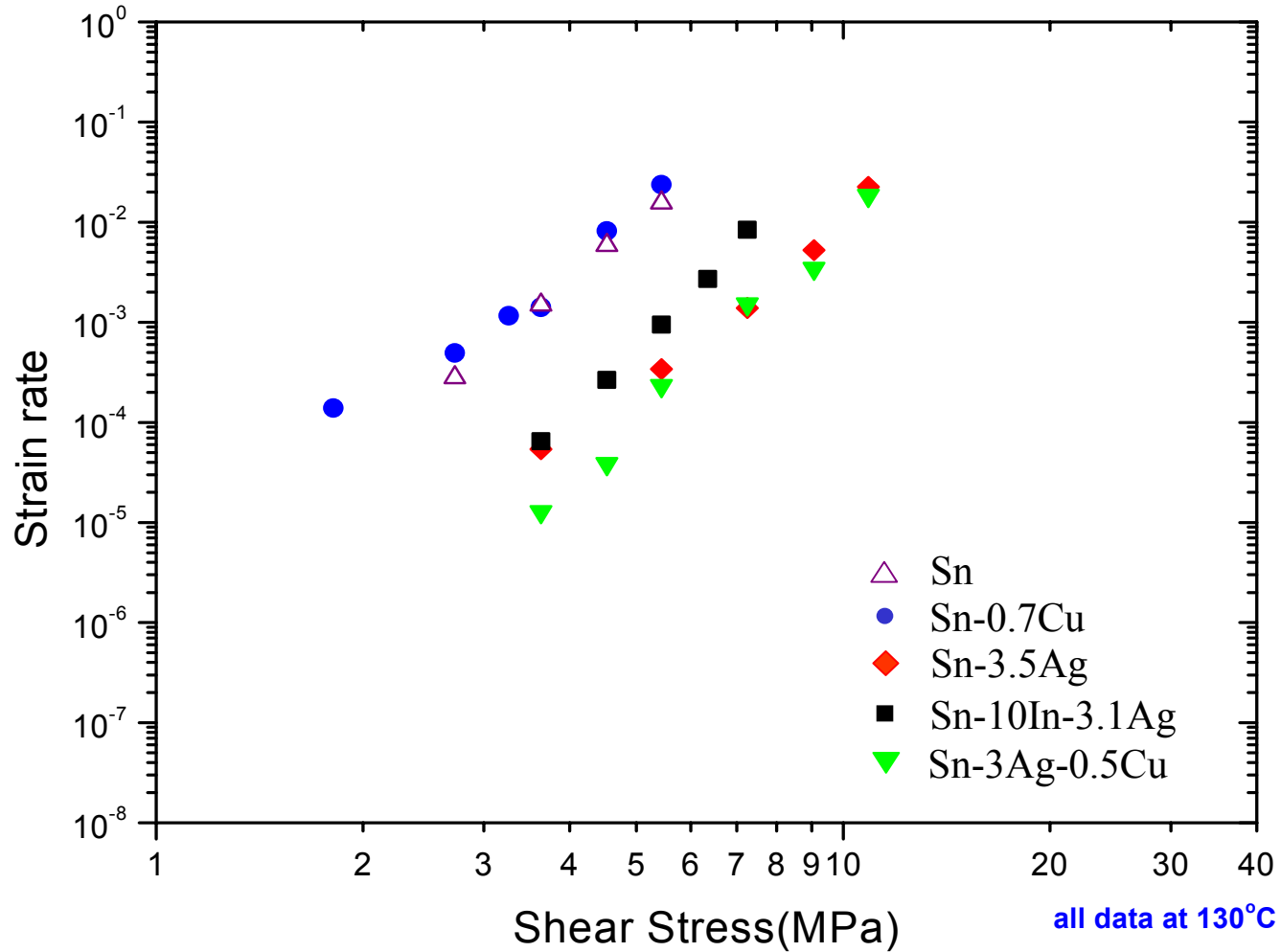
# Stress vs. Strain rate at 60°C



# Stress vs. Strain rate at 95°C

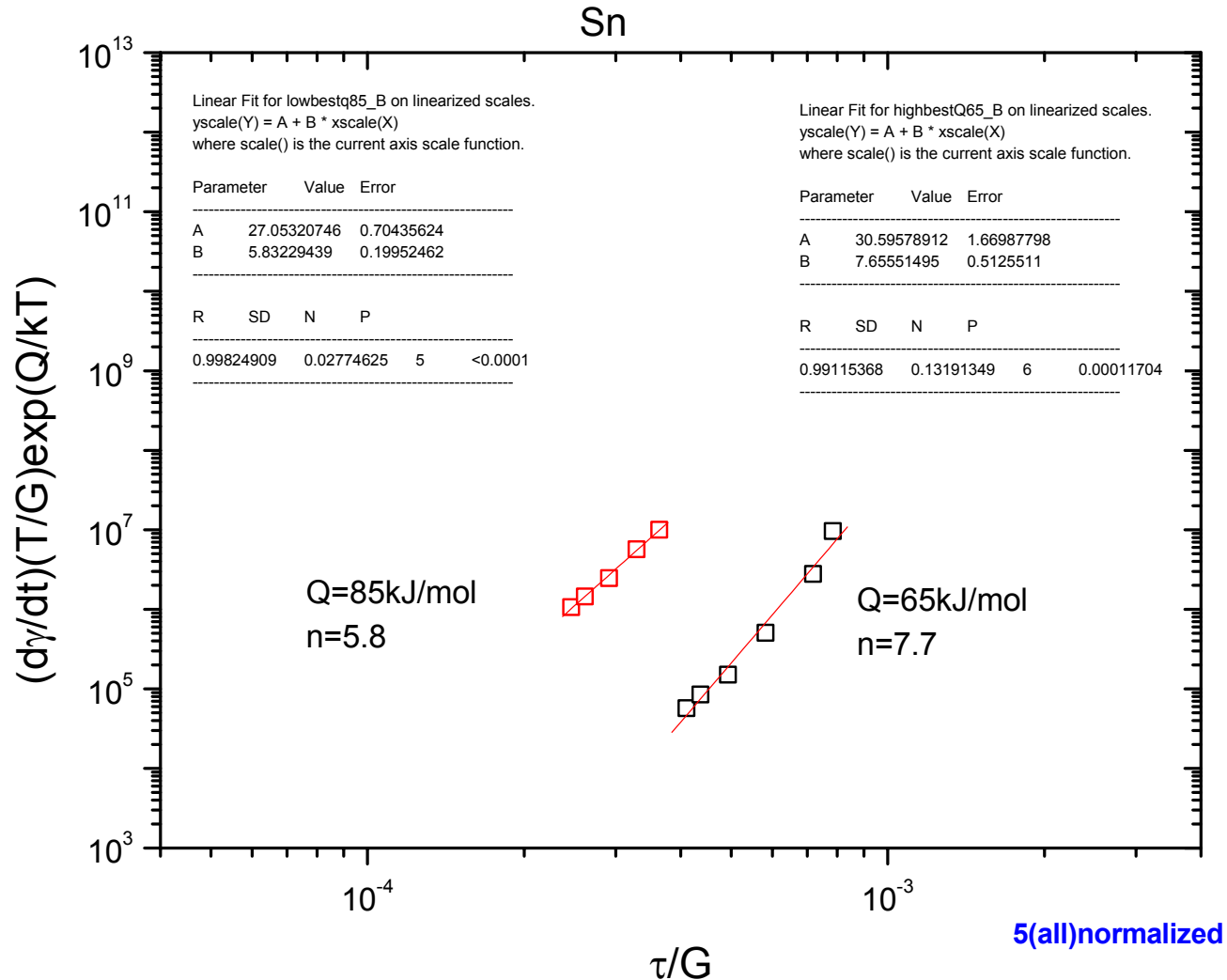


# Stress vs. Strain rate at 130°C





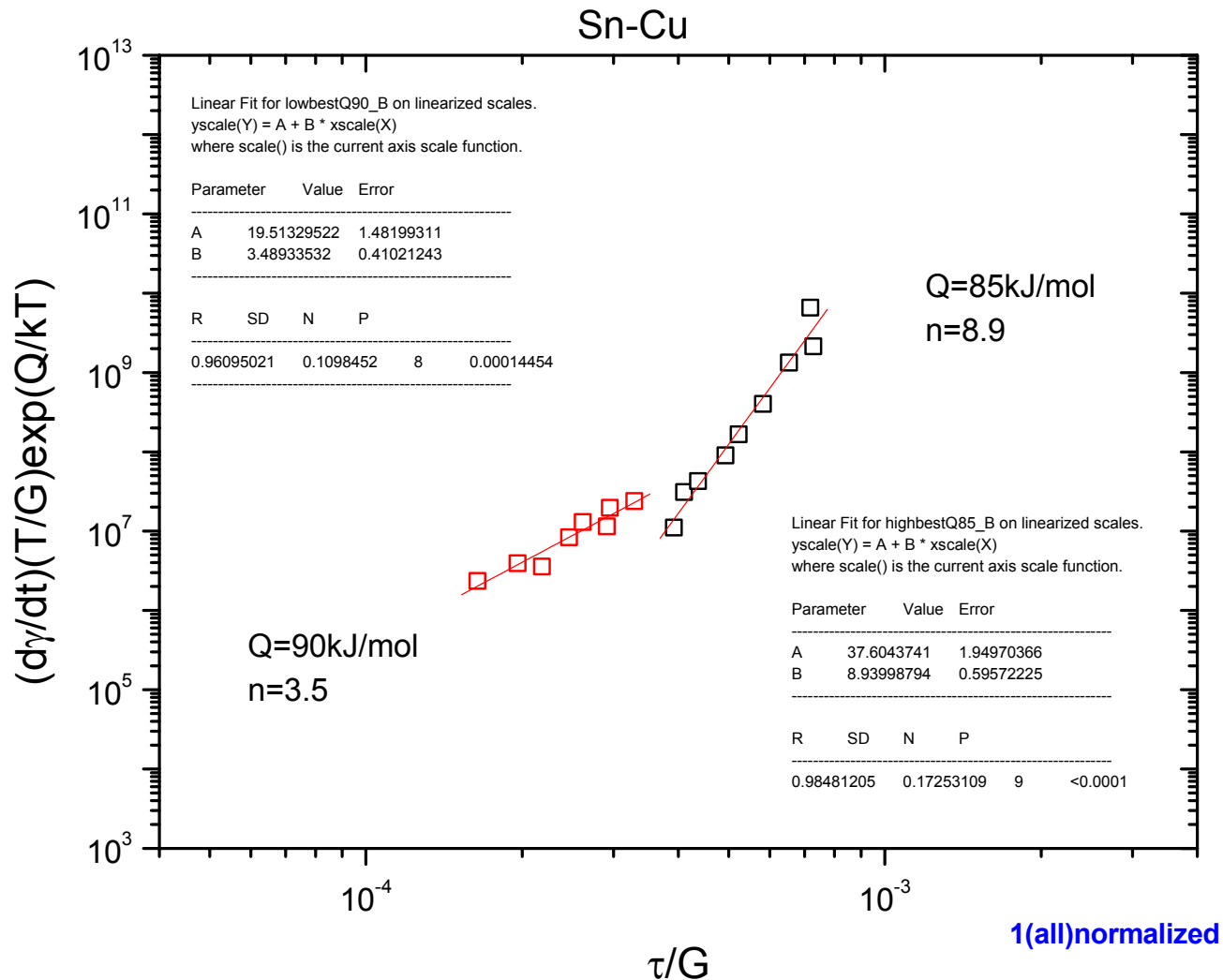
# Sn: Data normalized separately for high and low stress



\*  $G=16302-40.5T(^{\circ}\text{C})$

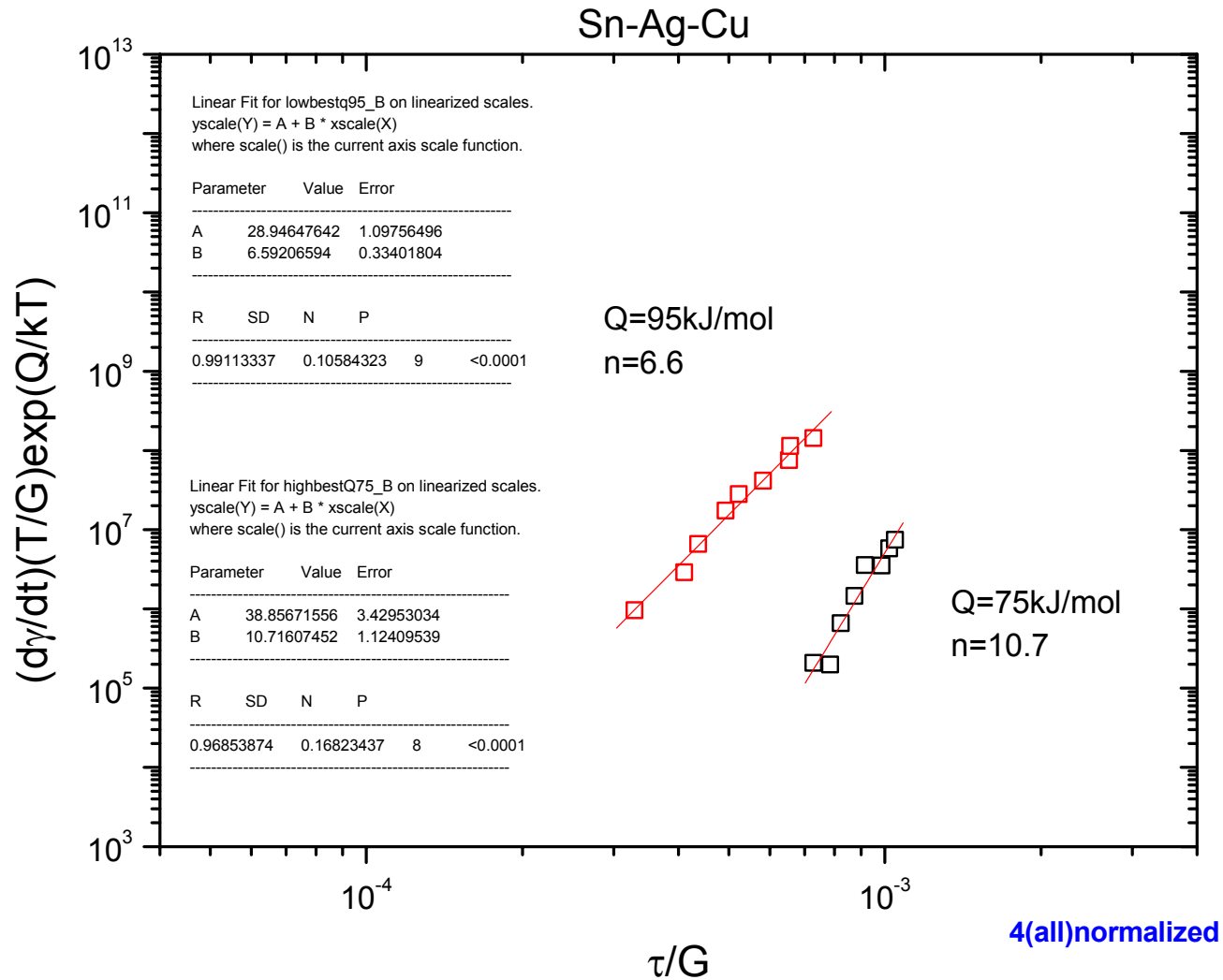
\*ignores abnormal three data points in the middle of 60°C data

# SnCu: Data normalized separately for high and low stress



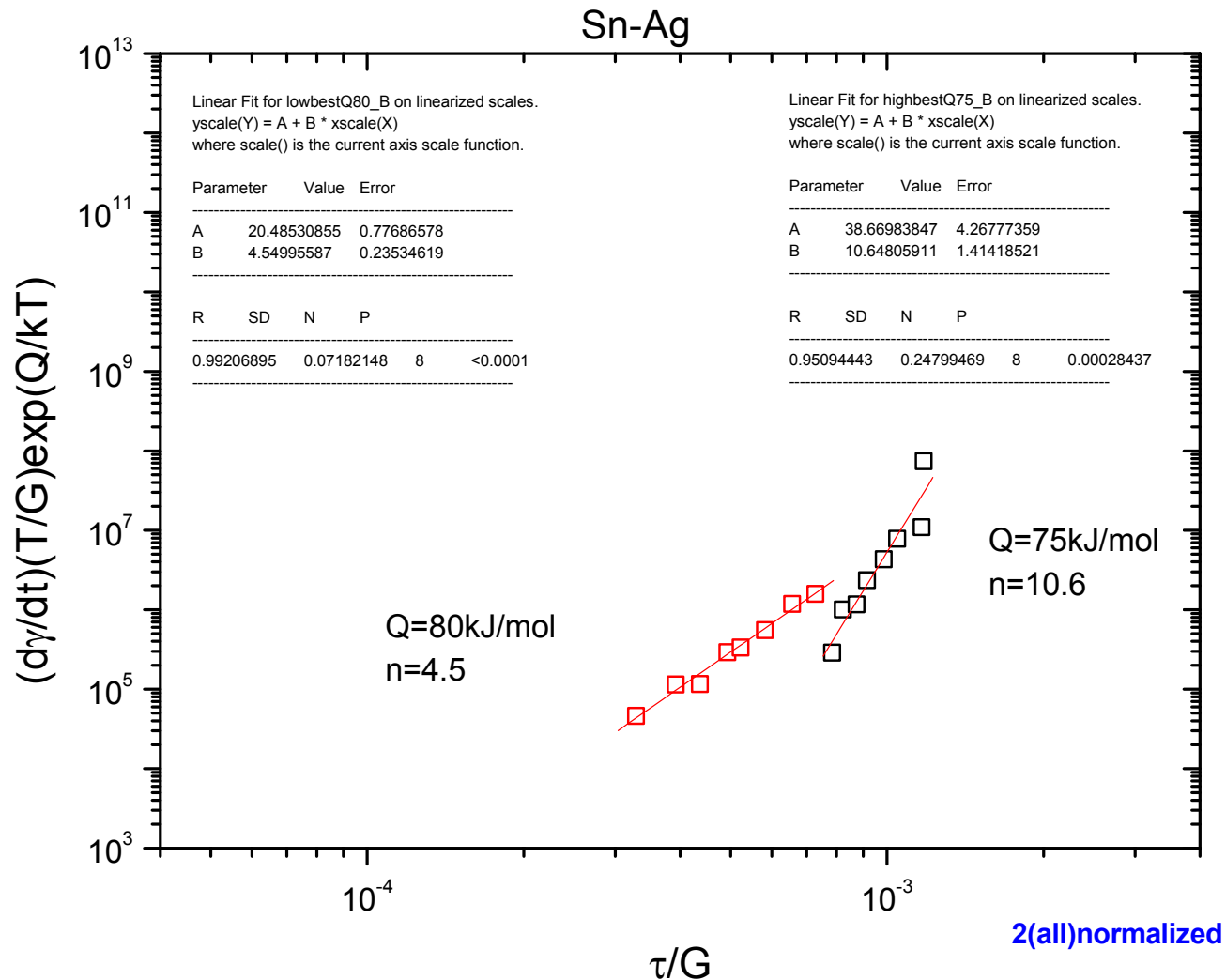
\*  $G=16302-40.5T(^{\circ}C)$

# SnAgCu: Data normalized separately for high and low stress



\*  $G=16302-40.5T(^{\circ}C)$

# SnAg: Data normalized separately for high and low stress



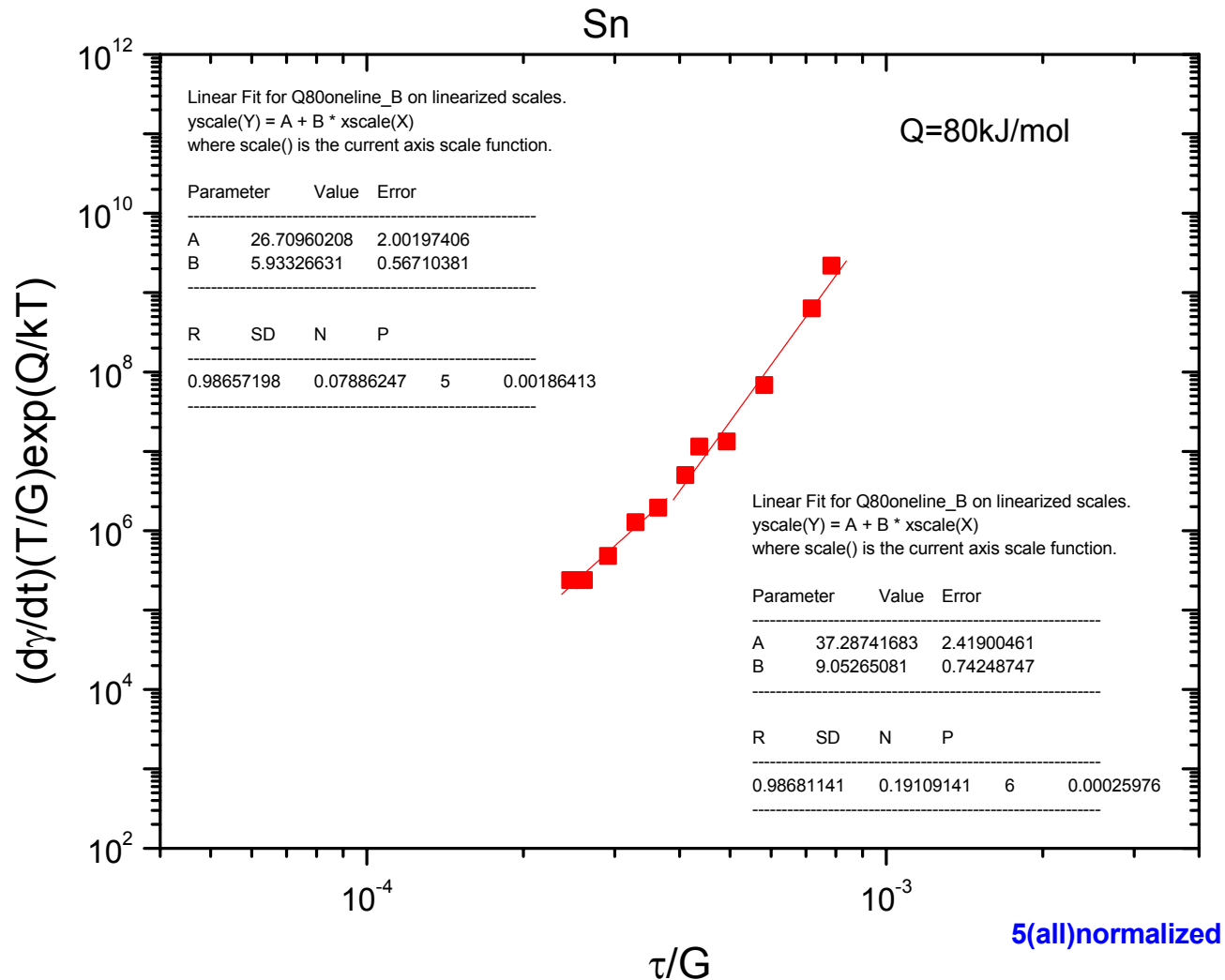
\*  $G=16302-40.5T(^{\circ}C)$

# Q-n Values from Normalized data

Solders	n		Q(KJ/mole)		$\tau/G$ at transition
	low	high	low	high	
Sn-Cu	3.5	8.9	90	85	$3\sim 4 \times 10^{-4}$
Sn-Ag	4.5	10.6	80	75	$7\sim 8 \times 10^{-4}$
Sn-In-Ag	5.4	9.5	100	115	$6\sim 7 \times 10^{-4}$
Sn-Ag-Cu	6.6	10.7	95	75	$7\sim 8 \times 10^{-4}$
Sn	5.8	7.7	85	65	$3\sim 4 \times 10^{-4}$

\* Based on Shear Modulus for Pure Sn,  $G=16302-40.5T(^{\circ}C)$

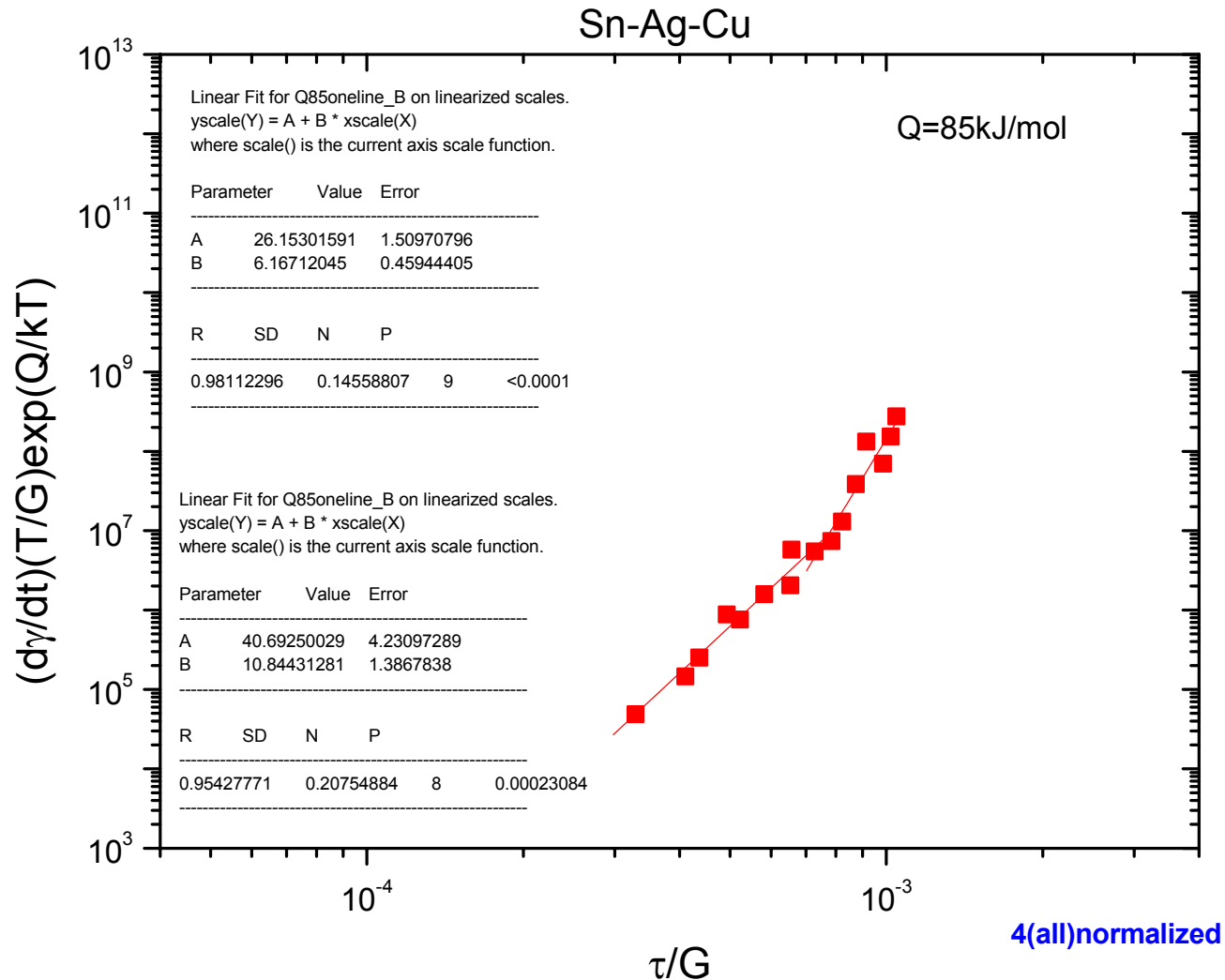
# Sn: Normalized data(when Q=80KJ/mole)



\*  $G=16302-40.5T(^{\circ}C)$

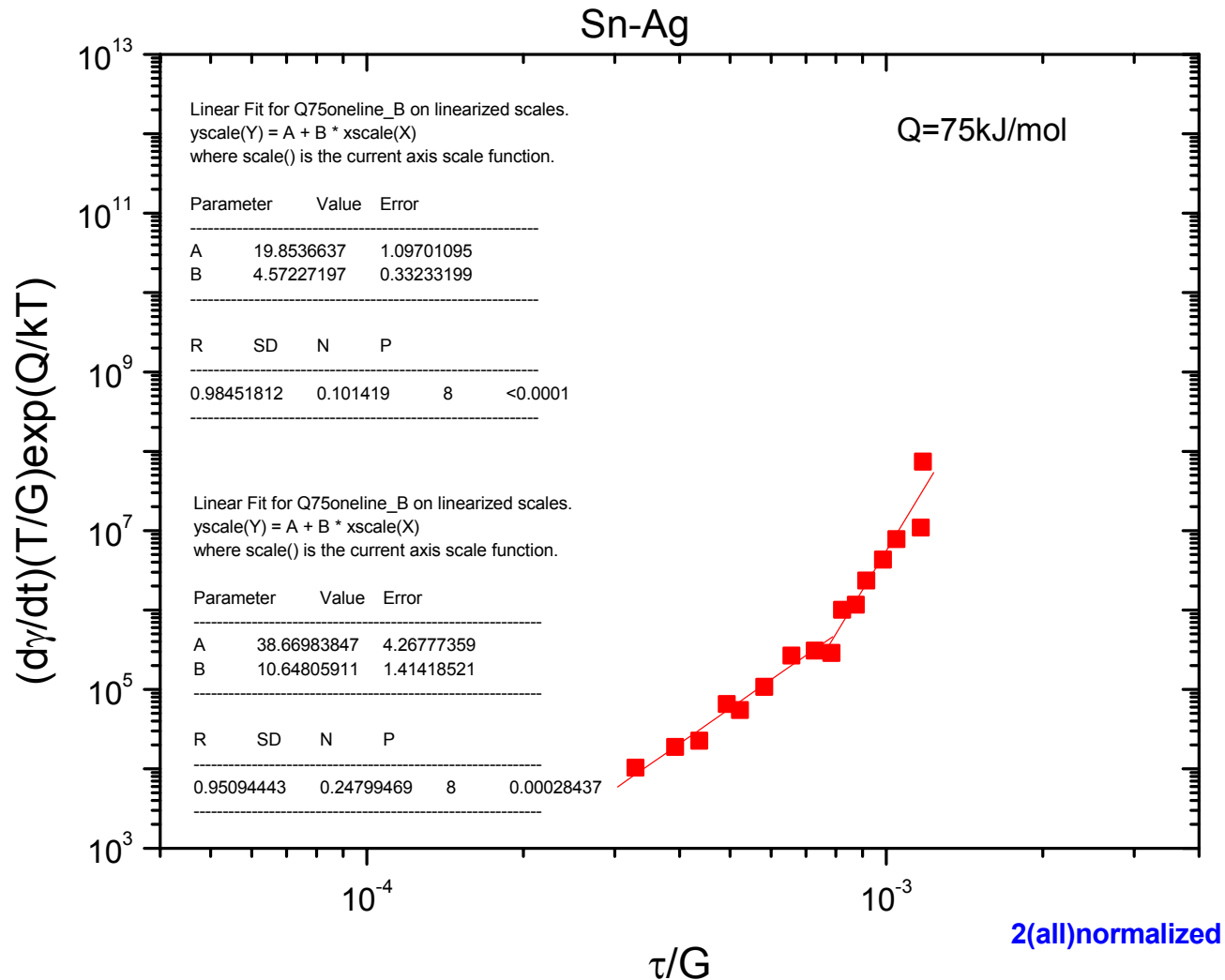
\*ignore abnormal three data points in the middle of 60°C data

# SnAgCu: Normalized data(Q=85KJ/mole)



\*  $G=16302-40.5T(^{\circ}C)$

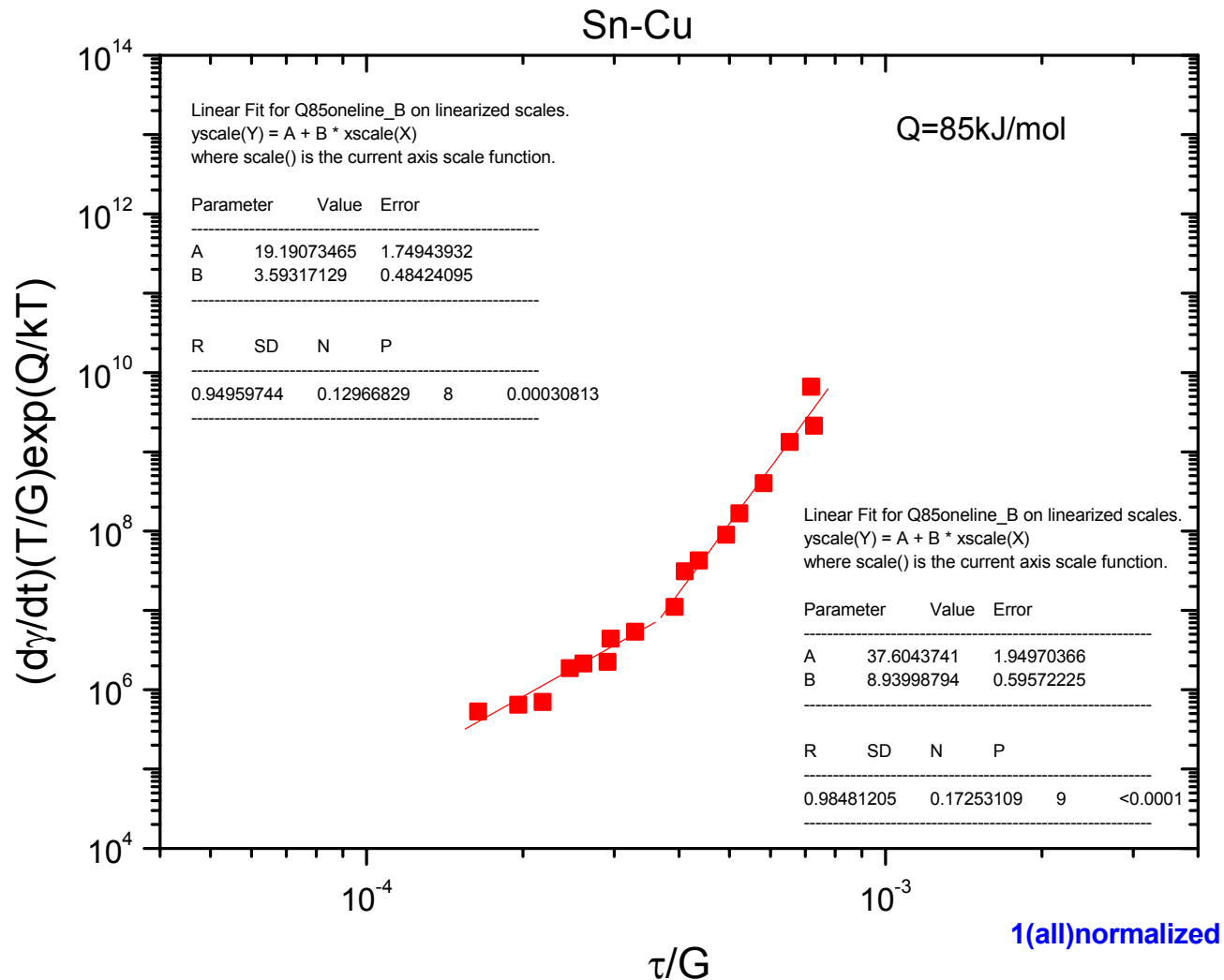
# SnAg: Normalized data( when Q=75KJ/mole)



\*  $G=16302-40.5T(^{\circ}C)$



# SnCu: Normalized data( when $Q=85\text{KJ/mole}$ )



\*  $G=16302-40.5T(^{\circ}\text{C})$

# Conclusion

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- Sn-rich solders show two regimes of steady-state creep behavior
  - $n_L \sim 3.5-6.5$  at low stress
  - $n_H \sim 8-11$  at high stress
  - Break at  $\tau/G \sim 4 \times 10^{-4}$  (Sn, SnCu),  $7 \times 10^{-4}$  (SnAgX)
- The high-stress exponent ( $n_H$ ) increases dramatically near room temperature
  - due to dominant Sn constituent
- Nonetheless, overall creep behavior is reasonably well fit by two-stage curve with  $Q \sim 80$  KJ/mole